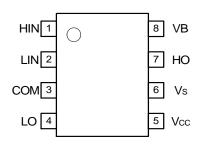


Pin Diagrams

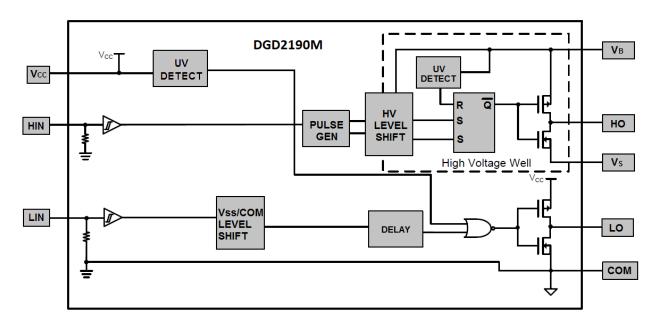


Top View: SO-8

Pin Descriptions

Pin Number	Pin Name	Function	
1	HIN	Logic Input for High-side Gate Driver Output, in Phase with HO	
2	LIN	Logic Input for Low-side Gate Driver Output, in Phase with LO	
3	COM	Low-Side and Logic Return	
4	LO	Low-Side Gate Drive Output	
5	V _{CC}	Low-Side and Logic Fixed Supply	
6	Vs	High-Side Floating Supply Return	
7	HO	High-Side Gate Drive Output	
8	VB	High-Side Floating Supply	

Functional Block Diagram





Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
High-Side Floating Supply Voltage	VB	-0.3 to +624	V	
High-Side Floating Supply Offset Voltage	Vs	V _B -24 to V _B +0.3	V	
High-Side Floating Output Voltage	V _{HO}	V _S -0.3 to V _B +0.3	V	
Offset Supply Voltage Transient	dV _S / dt	50	V/ns	
Low-Side and Logic Fixed Supply Voltage	V _{CC}	-0.3 to +24	V	
Low-Side Output Voltage	V _{LO}	-0.3 to V _{CC} +0.3	V	
Logic Input Voltage (HIN and LIN)	V _{IN}	-0.3 to V _{CC} +0.3	V	

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	PD	0.625	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{0JA}	200	°C/W
Thermal Resistance, Junction to Case (Note 5)	R _{θJC}	45	°C/W
Operating Temperature	TJ	+150	ŝ
Storage Temperature Range	T _{STG}	-55 to +150	0

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High-Side Floating Supply Absolute Voltage	VB	V _S +10	V _S +20	V
High-Side Floating Supply Offset Voltage	Vs	(Note 6)	600	V
High-Side Floating Output Voltage	V _{HO}	Vs	VB	V
Low-Side Fixed Supply Voltage	Vcc	10	20	V
Low-Side Output Voltage	VLO	0	Vcc	V
Logic Input Voltage (HIN and LIN)	V _{IN}	0	5	V
Ambient Temperature	T _A	-40	+125	°C

Notes: 5. When mounted on a standard JEDEC 2-layer FR-4 board. 6. Logic operation for Vs of -5V to +600V.

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DC Electrical Characteristics (V_{BIAS} (V_{CC} , V_{BS}) = 15V, @T_A = +25°C, unless otherwise specified.) (Note 7)

Parameter	Symbol	Min	Тур	Max	Unit	Condition
Logic "1" Input Voltage (Note 8)	VIH	2.5	—	_	V	$V_{CC} = 10V$ to 20V
Logic "0" Input Voltage (Note 8)	V _{IL}	—	_	0.8	V	$V_{CC} = 10V$ to 20V
High Level Output Voltage, V _{BIAS} - V _O	V _{OH}	_	_	0.1	V	$I_O = 0 m A$
Low Level Output Voltage, V _O	V _{OL}	_	-	0.035	V	$I_O = 0 m A$
Offset Supply Leakage Current	I _{LK}	_	_	50	μA	$V_{B} = V_{S} = 600V$
Quiescent V _{BS} Supply Current	I _{BSQ}	_	45	80	μA	$V_{IN} = 0V \text{ or } 5V$
Quiescent V _{CC} Supply Current	ICCQ	_	75	200	μA	$V_{IN} = 0V \text{ or } 5V$
Logic "1" Input Bias Current	I _{IN+}	_	25	50	μA	$V_{IN} = 5V$
Logic "0" Input Bias Current	I _{IN-}	_	1.0	2.0	μA	$V_{IN} = 0V$
V _{BS} Supply Undervoltage Positive Going Threshold	V _{BSUV+}	7.6	8.4	9.8	V	—
V _{BS} Supply Undervoltage Negative Going Threshold	V _{BSUV-}	6.9	7.8	9.0	V	—
V _{CC} Supply Undervoltage Positive Going Threshold	V _{CCUV+}	7.6	8.4	9.8	V	—
V _{CC} Supply Undervoltage Negative Going Threshold	Vccuv-	6.9	7.8	9.0	V	—
) (and) (Lindow (alterna Livetorea)	V _{CCUVH}	—	0.6		V	—
V _{CC} and V _{BS} Undervoltage Hysteresis	VBSUVH		0.6	_	V	—
Output High Short Circuit Pulsed Current	I _{O+}	3.5	4.5	_	A	$V_0 = 0V, PW \le 10ms$
Output Low Short Circuit Pulsed Current	I _{O-}	3.5	4.5	_	А	V_0 = 15V, PW \leq 10ms

Notes: 7. The V_{IN} and I_{IN} parameters are applicable to the two logic pins; HIN and LIN. The V_O and I_O parameters are applicable to the respective output pins: HO and LO.

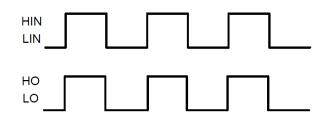
8. For optimal operation, it is recommended that the input pulses (HIN and LIN) should have a minimum amplitude of 2.5V with a minimum pulse width of 280ns.

AC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, C_L = 1000pF, @T_A = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Тур	Max	Unit	Condition
Turn-On Propagation Delay	ton	—	140	200	ns	$V_S = 0V$
Turn-Off Propagation Delay	t _{OFF}	—	140	200	ns	$V_{\rm S} = 0V$
Delay Matching, HO & LO Turn On/Off	t _{DM}	—		50	ns	—
Turn-On Rise Time	t _R	—	25	50	ns	$V_{S} = 0V$
Turn-Off Fall Time	t _F	—	20	45	ns	$V_{\rm S} = 0V$



Timing Waveforms





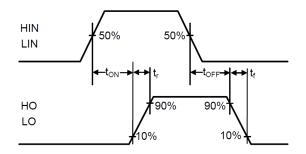


Figure 2. Switching Time Waveform Definitions

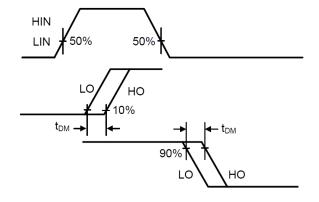


Figure 3. Delay Matching Waveform Definitions



Typical Performance Characteristics (Vcc=15V, @T_A = +25°C, unless otherwise specified.)

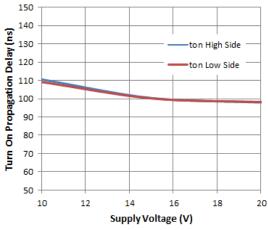


Figure 4. Turn-on Propagation Delay vs. Supply Voltage

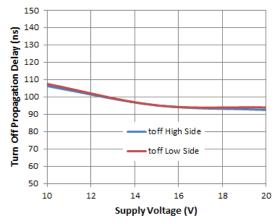
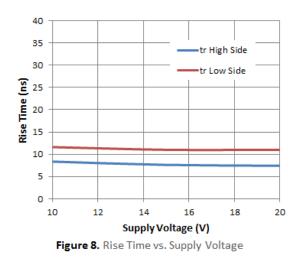


Figure 6. Turn-off Propagation Delay vs. Supply Voltage



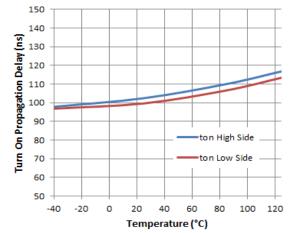


Figure 5. Turn-on Propagation Delay vs. Temperature

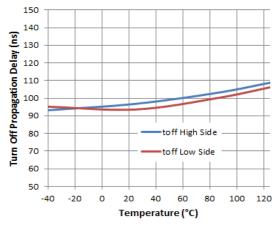
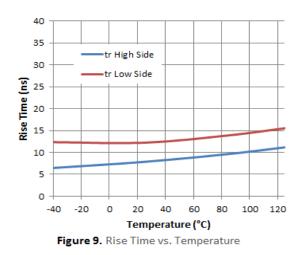


Figure 7. Turn-off Propagation Delay vs. Temperature





Typical Performance Characteristics (continued) (@T_A = +25°C, unless otherwise specified.)

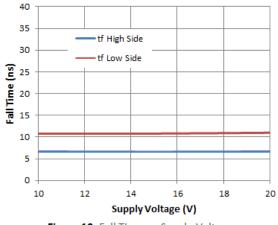


Figure 10. Fall Time vs. Supply Voltage

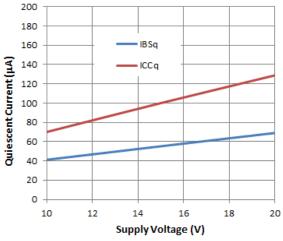
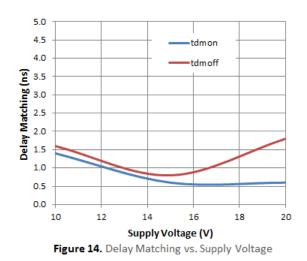


Figure 12. Quiescent Current vs. Supply Voltage



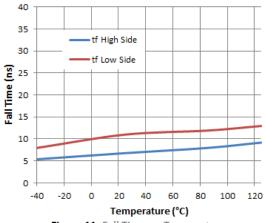
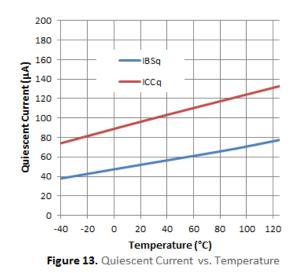
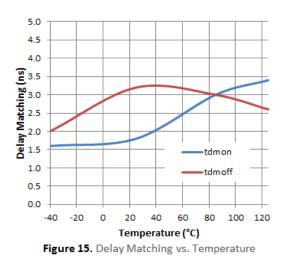


Figure 11. Fall Time vs. Temperature







Typical Performance Characteristics (continued) (@T_A = +25°C, unless otherwise specified.)

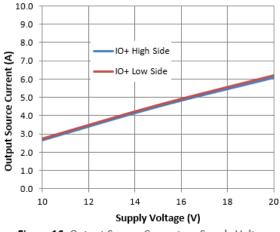


Figure 16. Output Source Current vs. Supply Voltage

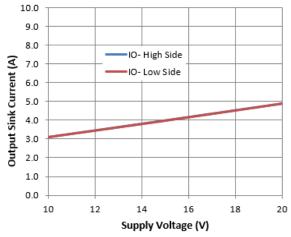


Figure 18. Output Sink Current vs. Supply Voltage

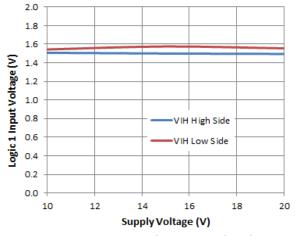


Figure 20. Logic 1 Input Voltage vs. Supply Voltage

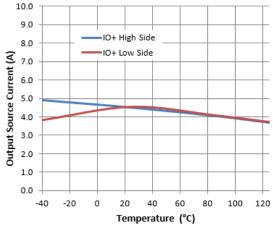
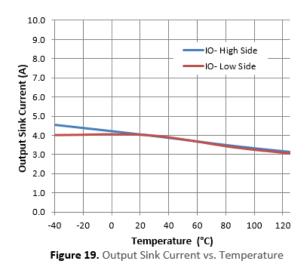
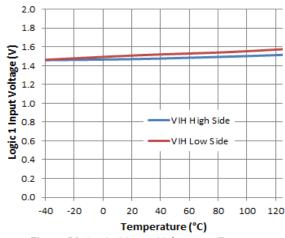
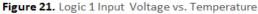


Figure 17. Output Source Current vs. Temperature









Typical Performance Characteristics (continued) (@T_A = +25°C, unless otherwise specified.)

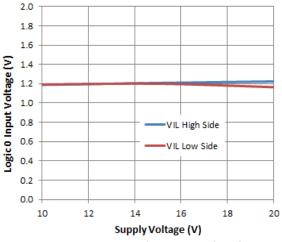
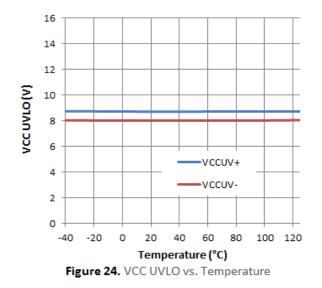


Figure 22. Logic 0 Input Voltage vs. Supply Voltage



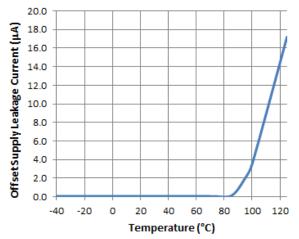


Figure 26. Offset Supply Leakage Current vs. Temperature

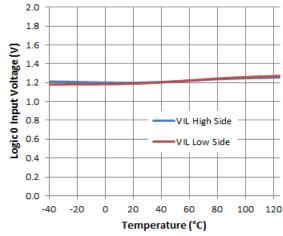
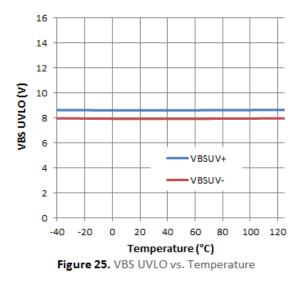


Figure 23. Logic 0 Input Voltage vs. Temperature





Max

1.75

0.25

0.51

0.248

5.00

6.20

4.00

_

0.50

1.27

8°

Тур

_

1.45

_

_

4.90

6.00

3.90

1.27

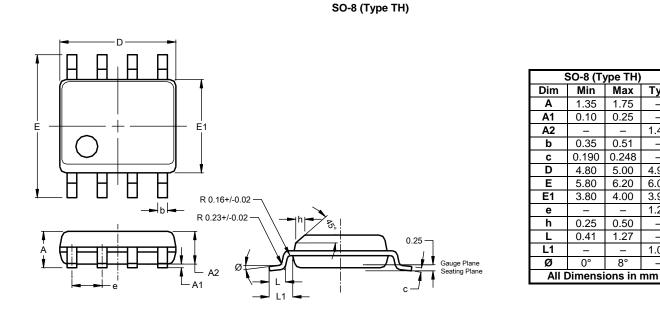
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1.04

Package Outline Dimensions

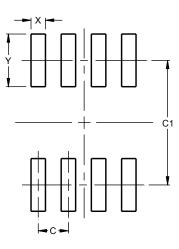
Please see http://www.diodes.com/package-outlines.html for the latest version.



Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8 (Type TH)



Dimensions	Value (in mm)			
С	1.27			
C1	5.20			
Х	0.60			
Y	2.20			

For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between Note: device Terminals and PCB tracking.



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